

## Sound Processor with Built-in 3-band Equalizer **BD37542FS**

#### **General Description**

BD37542FS is a sound processor with built-in 3-band equalizer for car audio. The functions are stereo input selector (which can switch single and ground isolation input), input-gain control, main volume, loudness, 5ch fader volume, LPF for subwoofer and mixing input. Moreover, "Advanced switch circuit", which is an original ROHM technology, can reduce various switching noise (ex. No-signal, low frequency like 20Hz & large signal inputs). Also, "Advanced switch" makes control of microcomputer easier, and can construct a high quality car audio system.

#### **Features**

- Reduced switching noise of input gain control, mute, main volume, fader volume, bass, middle, treble, loudness, mixing by using advanced switch circuit.
- Built-in differential input selector that can make various combination of single-ended / differential input.
- Built-in ground isolation amplifier inputs, which is ideal for external stereo input.
- Built-in input gain controller reduces switching noise for volume of a portable audio input.
- Decreased the number of external components due to built-in 3-band equalizer filter, LPF for subwoofer. It is possible to control Q, Gv, fo of 3-band equalizer, fc of LPF, and Gv of loudness by I<sup>2</sup>C BUS control.
- It is possible to adjust the gain of the bass, middle, treble up to ±20dB with 1 dB step gain adjustment.
- It is equipped with output terminals for Subwoofer. Moreover, the stereo signal output of the front and rear can also be chosen by the I<sup>2</sup>C BUS control.
- Built-in mixing input and mixing attenuator.
- Energy-saving design resulting in low-current consumption is achieved by utilizing the Bi-CMOS process. It has the advantage in guality over scaling down the power heat control of the internal regulators.
- Input terminals and output terminals are organized and separately laid out to keep the signal flow in one direction which results in simpler and smaller PCB layout.
- It is possible to control the I<sup>2</sup>C BUS by 3.3V / 5V.

## **Applications**

It is optimal for car audio systems. It can also be used for audio equipment of mini Compo, micro Compo, TV, etc.

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<ey sp<="" th=""><th>ecifications</th><th></th></ey>	ecifications	
	Power Supply Voltage Range:	7.0V to 9.5V
	Circuit Current (No Signal):	38mA(Typ)
	Total Harmonic Distortion 1:	
	(FRONT,REAR)	0.001%(Typ)
	Total Harmonic Distortion 2:	
	(SUBWOOFER)	0.002%(Typ)
	Maximum Input Voltage:	2.3Vrms (Typ)
	Cross-talk Between Selectors:	-100dB (Typ)
	Volume Control Range:	+15 dB to -79dB
	Output Noise Voltage 1:	
	(FRONT,REAR)	3.8µVrms(Typ)
	Output Noise Voltage 2:	
	(SUBWOOFER)	4.8µVrms(Typ)
	Residual Output Noise Voltage:	1.8µVrms(Typ)
-	Operating Temperature Bange	-40°C to +85°C

Operating Temperature Range: -40°C to +85°C

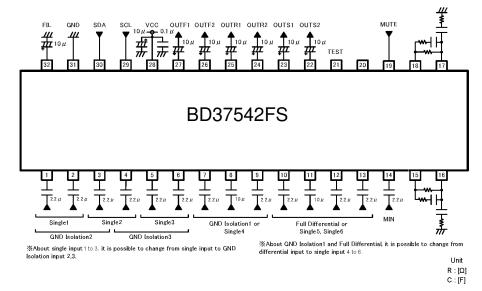
#### Package

#### W(Typ) x D(Typ) x H(Max)

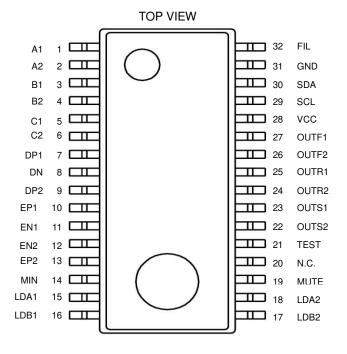


OProduct structure : Silicon monolithic integrated circuit OThis product has no designed protection against radioactive rays

## **Typical Application Circuit**



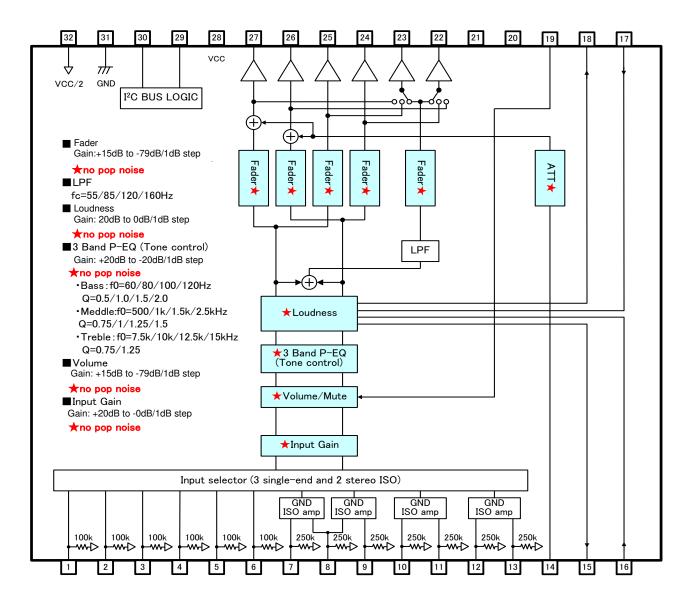
## **Pin Configuration**



#### **Pin Descriptions**

r in Desch	plions				
Pin No.	Pin Name	Description	Pin No.	Pin Name	Description
1	A1	A input terminal of 1ch	17	LDB2	Loudness setting terminal of 2ch
2	A2	A input terminal of 2ch	18	LDA2	Loudness setting terminal of 2ch
3	B1	B input terminal of 1ch	19	MUTE	External compulsory mute terminal
4	B2	B input terminal of 2ch	20	N.C.	No Connection
5	C1	C input terminal of 1ch	21	TEST	Test Pin
6	C2	C input terminal of 2ch	22	OUTS2	Subwoofer output terminal of 2ch
7	DP1	D positive input terminal of 1ch	23	OUTS1	Subwoofer output terminal of 1ch
8	DN	D negative input terminal	24	OUTR2	Rear output terminal of 2ch
9	DP2	D positive input terminal of 2ch	25	OUTR1	Rear output terminal of 1ch
10	EP1	E positive input terminal of 1ch	26	OUTF2	Front output terminal of 2ch
11	EN1	E negative input terminal of 1ch	27	OUTF1	Front output terminal of 1ch
12	EN2	E negative input terminal of 2ch	28	VCC	Power supply terminal
13	EP2	E positive input terminal of 2ch	29	SCL	I <sup>2</sup> C Communication clock terminal
14	MIN	Mixing input terminal	30	SDA	I <sup>2</sup> C Communication data terminal
15	LDA1	Loudness setting terminal of 1ch	31	GND	GND terminal
16	LDB1	Loudness setting terminal of 1ch	32	FIL	VCC/2 terminal

## **Block Diagram**



## Absolute Maximum Ratings (Ta=25°C)

Parameter Symbol Rating		Rating	Unit
Power Supply Voltage Vcc		10.0	V
Input Voltage	VIN	Vcc+0.3 to GND-0.3	V
Power Dissipation	Pd	0.95 (Note 1)	W
Storage Temperature	Tstg	-55 to +150	°C

(Note 1) When mounted on the standard board (70 x 70 x 1.6 mm<sup>3</sup>), derate by 7.6mW/°C for Ta above 25°C.

Thermal resistance  $\theta_{ja} = 131.6(^{\circ}C/W)$ 

Material : A FR4 grass epoxy board(3% or less of copper foil area)

**Caution:** Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

## **Recommended Operating Conditions**

Parameter	Symbol	Min	Тур	Max	Unit
Power Supply Voltage	Vcc	7.0	-	9.5	V
Temperature	Topr	-40	-	+85	°C

## **Electrical Characteristics**

(Unless specified otherwise, Ta=25°C, V<sub>CC</sub>=8.5V, f=1kHz, V<sub>IN</sub>=1Vrms, Rg=600Ω, RL=10kΩ, A1 input, Input gain 0dB, Mute OFF, Volume 0dB, Tone control 0dB, Loudness 0dB, LPF OFF, Mixing OFF, Fader 0dB)

BLOCK	Parameter	Symbol	,	Limit	,	Unit	Conditions
BLC	Parameter	Зушоо	Min	Тур	Max	Unit	Conditions
	Circuit Current (No Signal)	la	-	38	48	mA	No signal
	Voltage Gain	Gv	-1.5	0	+1.5	dB	Gv=20log(V <sub>OUT</sub> /V <sub>IN</sub> )
	Channel Balance	СВ	-1.5	0	+1.5	dB	CB = Gv1-Gv2
	Total Harmonic Distortion 1 (FRONT,REAR)	THD+N1	-	0.001	0.05	%	V <sub>OUT</sub> =1Vrms BW=400Hz-30KHz
	Total Harmonic Distortion 2 (SUBWOOFER)	THD+N2	-	0.002	0.05	%	V <sub>OUT</sub> =1Vrms BW=400Hz-30KHz
GENERAL	Output Noise Voltage 1 (FRONT,REAR) *	V <sub>NO1</sub>	-	3.8	15	μVrms	Rg = 0Ω BW = IHF-A
GENI	Output Noise Voltage 2 (SUBWOOFER) *	V <sub>NO2</sub>	-	4.8	15	μVrms	Rg = 0Ω BW = IHF-A
	Residual Output Noise Voltage *	V <sub>NOR</sub>	-	1.8	10	μVrms	Fader = -∞dB Rg = 0Ω BW = IHF-A
	Crosstalk Between Channels *	СТС	-	-100	-90	dB	$\begin{array}{l} \text{Rg} = 0\Omega \\ \text{CTC} = 20 \text{log}(V_{\text{OUT}} / V_{\text{IN}}) \\ \text{BW} = \text{IHF-A} \end{array}$
	Ripple Rejection	RR	-	-70	-40	dB	f=1kHz V <sub>RR</sub> =100mVrms RR=20log(V <sub>CC</sub> IN/Vоυт)
	Input Impedance(A, B,C)	R <sub>IN_s</sub>	70	100	130	kΩ	
~	Input Impedance(D, E)	RIN_D	175	250	325	kΩ	
SELECTOR	Maximum Input Voltage	V <sub>IM</sub>	2.1	2.3	-	Vrms	V <sub>IM</sub> at THD+N(V <sub>OUT</sub> )=1% BW=400Hz-30KHz
UT SELI	Crosstalk Between Selectors *	CTS	-	-100	-90	dB	$\begin{array}{l} Rg = 0\Omega \\ CTS = 20 log(V_{OUT}/V_{IN}) \\ BW = IHF-A \end{array}$
INPUT	Common Mode Rejection Ratio *	CMRR	50	65	-	dB	XP1 and XN input XP2 and XN input CMRR=20log(V <sub>IN</sub> /V <sub>OUT</sub> ) BW = IHF-A,[*X…D,E]

## **Electrical Characteristics - continued**

BLOCK	Parameter	Symbol		Limit		Unit	Conditions		
BL(		Cynibol	Min	Тур	Max	Chit	Conditions		
AIN	Minimum Input Gain	Gin_min	-2	0	+2	dB	Input gain 0dB V <sub>IN</sub> =100mVrms G <sub>IN</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> )		
INPUT GAIN	Maximum Input Gain	Gin_max	18	20	22	dB	Input gain 20dB V <sub>IN</sub> =100mVrms G <sub>IN</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> )		
_	Gain Set Error	$G_{\text{IN}\_\text{ERR}}$	-2	0	+2	dB	GAIN=+1dB to +20dB		
MUTE	Mute Attenuation *	G <sub>MUTE</sub>	-	-105	-85	dB	Mute ON G <sub>MUTE</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> ) BW = IHF-A		
	Maximum Gain	Gv max	13	15	17	dB	Volume = $15dB$ V <sub>IN</sub> =100mVrms Gv=20log(V <sub>OUT</sub> /V <sub>IN</sub> )		
VOLUME	Maximum Attenuation *	Gv_min	-	-100	-85	dB	$      Volume = -∞dB \\       G_V=20log(V_{OUT}/V_{IN}) \\       BW = IHF-A $		
NOL	Attenuation Set Error 1	Gv_err1	-2	0	+2	dB	GAIN & ATT=+15dB to -15dB		
	Attenuation Set Error 2	Gv_err2	-3	0	+3	dB	ATT=-16dB to -47dB		
	Attenuation Set Error 3	Gv_err3	-4	0	+4	dB	ATT=-48DB to -79DB		
	Maximum Boost Gain	GB_BST	18	20	22	dB	$\begin{array}{l} \mbox{Gain}{=}+20dB\ f{=}100Hz \\ \mbox{V}_{IN}{=}100mVrms \\ \mbox{G}_{B}{=}20log\ (V_{OUT}/V_{IN}) \\ \mbox{Gain}{=}{-}20dB\ f{=}100Hz \\ \mbox{V}_{IN}{=}2Vrms \\ \mbox{G}_{B}{=}20log\ (V_{OUT}/V_{IN}) \end{array}$		
BASS	Maximum Cut Gain	G <sub>B_CUT</sub>	-22	-20	-18	dB			
	Gain Set Error	Gb_err	-2	0	+2	dB	Gain=-20dB to +20dB f=100Hz		
щ	Maximum Boost Gain	<b>G</b> м_вsт	18	20	22	dB	Gain=+20dB f=1kHz V <sub>IN</sub> =100mVrms G <sub>M</sub> =20log (V <sub>OUT</sub> /V <sub>IN</sub> )		
MIDDLE	Maximum Cut Gain	<b>G</b> м_сит	-22	-20	-18	dB	$\begin{array}{l} \text{Gain=-20dB f=1kHz} \\ \text{V}_{\text{IN}=2\text{Vrms}} \\ \text{G}_{\text{M}=20\text{log}} \left(\text{V}_{\text{OUT}}/\text{V}_{\text{IN}}\right) \end{array}$		
	Gain Set Error	Gm_err	-2	0	+2	dB	Gain=-20dB to +20dB f=1kHz		
щ	Maximum Boost Gain	Gt_bst	18	20	22	dB	Gain=+20dB f=10kHz V <sub>IN</sub> =100mVrms GT=20log (V <sub>OUT</sub> /V <sub>IN</sub> )		
TREBLE	Maximum Cut Gain	Gt_cut	-22	-20	-18	dB	$\begin{array}{l} \mbox{Gain=-20dB f=10kHz} \\ \mbox{V}_{\text{IN}} = 2 \mbox{Vrms} \\ \mbox{G}_{\text{T}} = 20 \mbox{log} \ (\mbox{V}_{\text{OUT}} / \mbox{V}_{\text{IN}}) \end{array}$		
	Gain Set Error	GT_ERR	-2	0	+2	dB	Gain=-20dB to +20dB f=10kHz		
	Input Impedance	RIN_M	19	27	35	kΩ			
NG	Maximum Input Voltage	Vim_m	2.0	2.2	-	Vrms	V <sub>IM</sub> at THD+N(V <sub>OUT</sub> )=1% BW=400Hz-30KHz		
MIXING	Maximum Attenuation	GMX_MIN	-	-100	-85	dB	MIX=OFF G <sub>MX</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> ) BW=INF-A		
	Maximum Gain	<b>G</b> мх_мах	5	7	9	dB	ATT=+6dB G <sub>MX</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> )		

## **Electrical Characteristics - continued**

BLOCK	Doromotor	Cumbol		Limit		Linit	Conditions
BLG	Parameter	Symbol	Min	Тур	Max	Unit	Conditions
	Maximum Boost Gain	G <sub>F_BST</sub>	13	15	17	dB	Fader=15dB V <sub>IN</sub> =100mVrms G <sub>F</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> )
SUBWOOFER	Maximum Attenuation *	GF_MIN	-	-100	-90	dB	Fader = -∞dB G <sub>F</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> ) BW = IHF-A
BWG	Gain Set Error	GF_ERR	-2	0	+2	dB	Gain=+1dB to +15dB
/SU	Attenuation Set Error 1	GF_ERR1	-2	0	+2	dB	ATT=-1dB to -15dB
EB	Attenuation Set Error 2	GF_ERR2	-3	0	+3	dB	ATT=-16dB to -47dB
FAD	Attenuation Set Error 3	GF_ERR3	-4	0	+4	dB	ATT=-48dB to -79dB
	Output Impedance	Rout	-	-	50	Ω	V <sub>IN</sub> =100mVrms
	Maximum Output Voltage	V <sub>ОМ</sub>	2	2.2	-	Vrms	THD+N=1% BW=400Hz-30KHz
LOUDNESS	Maximum Gain	Gl_max	17	20	23	dB	Gain 20dB V <sub>IN</sub> =100mVrms GL=20log(V <sub>OUT</sub> /V <sub>IN</sub> )
	Gain Set Error	GL_ERR	-2	0	+2	dB	Gain=+1dB to +20dB

VP-9690A(Average value detection, effective value display) filter by Matsushita Communication is used for \* measurement. Phase between input / output is same.

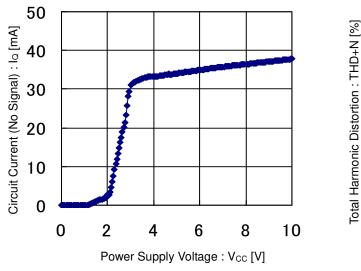
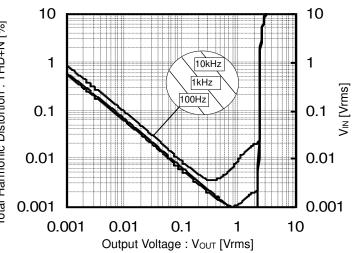
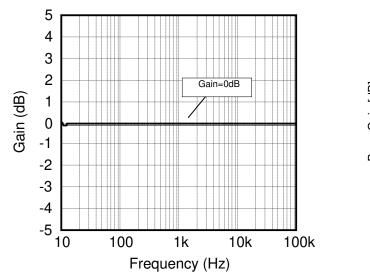
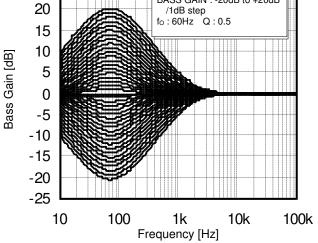


Figure 1. Circuit Current (No Signal) vs Power Supply Voltage









BASS GAIN : -20dB to +20dB

Figure 3. Gain vs Frequency

Figure 4. Bass Gain vs Frequency

25

20

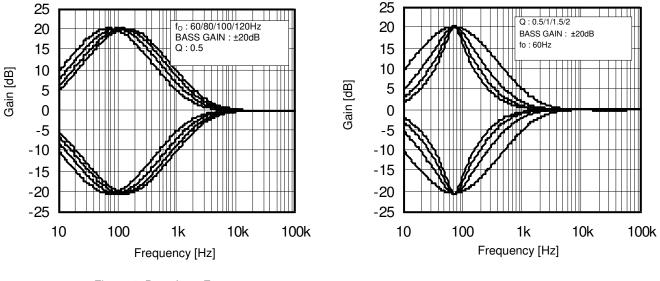


Figure 5. Bass fo vs Frequency



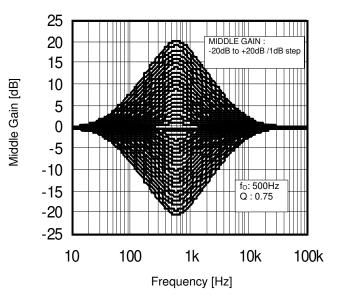


Figure 7. Middle Gain vs Frequency

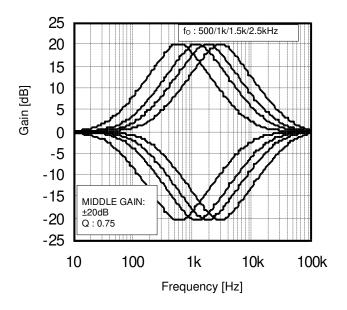
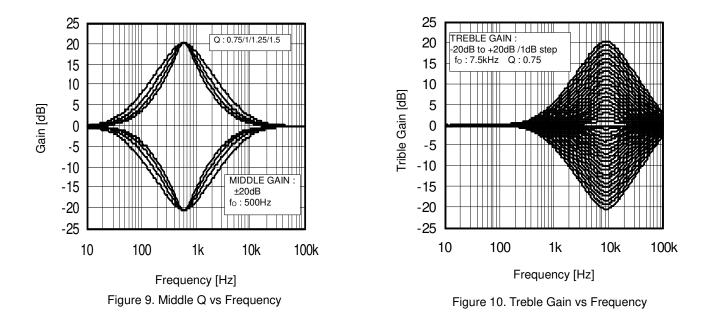
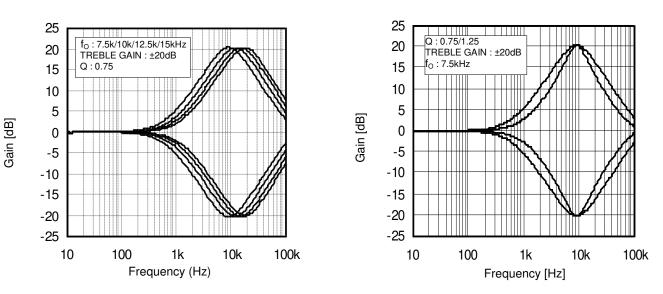
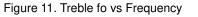
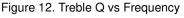


Figure 8. Middle fo vs Frequency









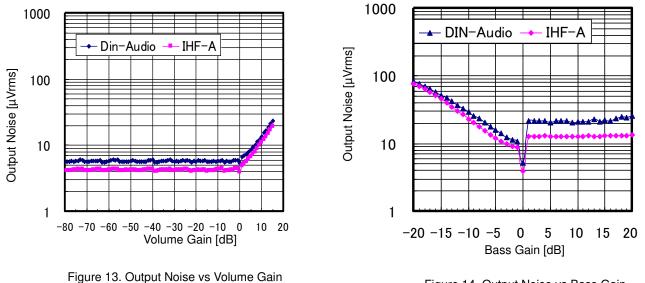


Figure 14. Output Noise vs Bass Gain

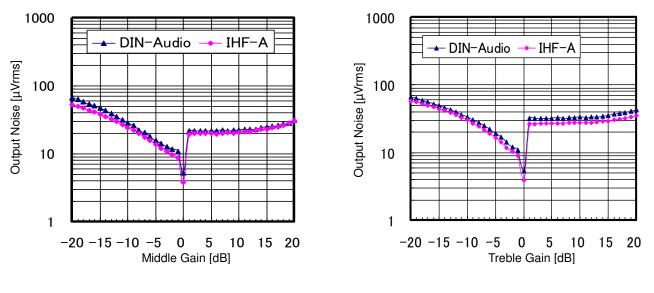


Figure 15. Output Noise vs Middle Gain



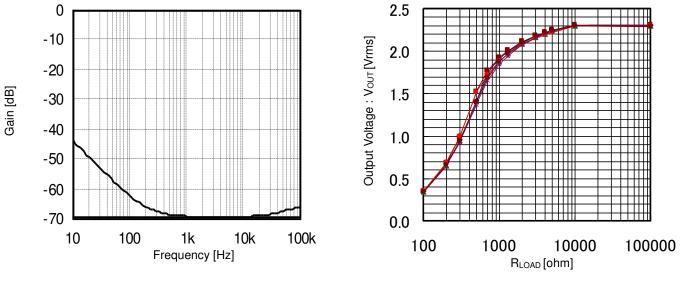


Figure 17. CMRR vs Frequency

Figure 18. Output Voltage vs RLOAD

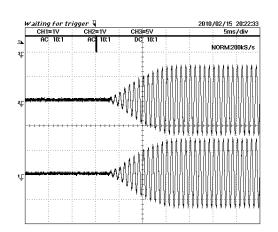


Figure 19. Advanced Switch 1

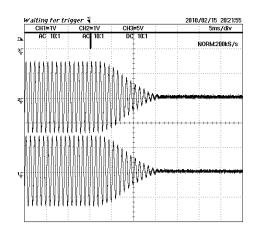


Figure 20. Advanced Switch 2

## **Timing Chart**

## **CONTROL SIGNAL SPECIFICATION**

(1) Electrical Specifications and Timing for Bus Lines and I/O Stages

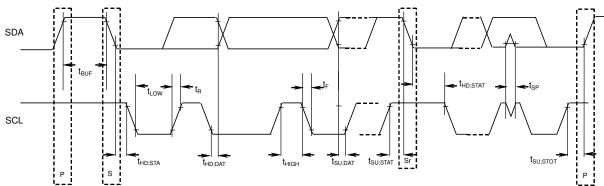


Figure 21. I<sup>2</sup>C-bus Signal Timing Diagram

Table 1 Characteristics of the SDA and SCL bus lines for I<sup>2</sup>C-bus devices (Ta=25°C, V<sub>CC</sub>=8.5V)

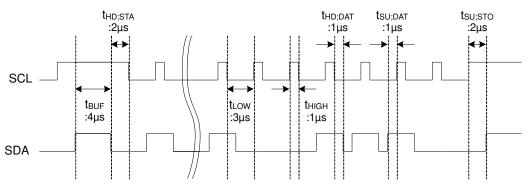
	Parameter	Symbol	Fast-mode	Unit	
	Faldinelei	Symbol	Min	Max	Unit
1	SCL clock frequency	fscl	0	400	kHz
2	Bus free time between a STOP and START condition	t <sub>BUF</sub>	1.3	-	μS
3	Hold time (repeated) START condition. After this period, the first clock	thd:sta	0.6	-	μS
-	pulse is generated	110,011			P
4	LOW period of the SCL clock	t∟ow	1.3	-	μS
5	HIGH period of the SCL clock	tнigн	0.6	-	μS
6	Set-up time for a repeated START condition	tsu;sta	0.6	-	μS
7	Data hold time:	thd;dat	0.06 (Note)	-	μS
8	Data set-up time	tsu;dat	120	-	ns
9	Set-up time for STOP condition	tsu;sто	0.6	-	μS

All values refer to VIH Min and VIL Max Levels (see Table 2).

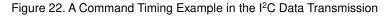
(Note) A device must internally provide a hold time of at least 300 ns for the SDA signal (referred to the VIH Min of the SCL signal) in order to bridge the undefined region of the falling edge of SCL. For 7(tHD:DAT), 8(tsU:DAT), make the setup in which the margin is full.

## Table 2 Characteristics of the SDA and SCL I/O stages for I<sup>2</sup>C-bus devices

	Devemeter	Sumbol	Fast-mode	Unit	
	Parameter	Symbol	Min	Max	Unit
10	LOW level input voltage:	VIL	-0.3	+1	V
11	HIGH level input voltage:	Vін	2.3	5	V
12	Pulse width of spikes which must be suppressed by the input filter.	tsp	0	50	ns
13	LOW level output voltage: at 3mA sink current	V <sub>OL1</sub>	0	0.4	V
14	Input current each I/O pin with an input voltage between 0.4V and 4.5V.	lı –	-10	+10	μA



SCL clock frequency : 250kHz



## (2) <u>I<sup>2</sup>C BUS FORMAT</u>

Μ	SB LSB		MSB	LSB		MSB	L	SB			
S	Slave Address	Α	Select Ad	dress	Α		Data		Α	Р	
1bit	8bit	1bit	8b	oit	1bit		8bit		1bit	1bit	
	S	= Sta	rt condition (I	Recognitic	on of a	start bit)					
	Slave Address	= Recognition of slave address. The first 7 bits correspond to the slave address.									
	The least significant bit is "L" which corresponds to write mode.										
	А	= ACI	KNOWLÈDG	DWLEDGE bit (Recognition of acknowledgement)							
	Select Address	= Sel	ect address o	correspond	ding t	o volum	ie, bass or tr	eble.			
	Data	= Data on every volume and tone.									
	Р	= Stop condition (Recognition of stop bit)									

(3) <u>I<sup>2</sup>C BUS Interface Protocol</u>

(a) Basic Format

(4)	Suble i ennat									
S	Slave Addr	ess	Α	Select Addres	S	Α	Data	Α	Р	
	MSB	LSB		MSB	LSB	Ν	ASB L	SB.		

(b	) Automatic Increment	Select Address increases	(+1	) according to the number of data.)
<b>~</b>			( ' '	

S	Slave Add	ress	А	Select Ad	dress	А	Data	a1	А	Data2	А	 DataN	А	Ρ
	MSB	LSB		MSB	LSB		MSB	LSE	3	MSB	LSB	MSB		SB

(Example) ①Data1 shall be set as data of address specified by Select Address.

②Data2 shall be set as data of address specified by Select Address +1.

3DataN shall be set as data of address specified by Select Address +N-1.

(c) Configuration Unavailable for Transmission (In this case, only Select Address1 is set.)

S	Slave A	ddress A	A Select	Address1	Α	Data	А	Select A	Address 2	А	Data	Α	Ρ
	MSB	LSB	MSB	LSB	Μ	SB LSE	3	MSB	LSB	Ν	/ISB L	SB	
	(No	te )If any d	data is tran	smitted as S	elec	ct Addres	s 2 I	next to da	ata, it is reco	gni	zed		
		as dat	ta, not as S	elect Addre	ss 2	<u>)</u> .							

## (4) Slave Address

MSB							LSB	
A6	A5	A4	A3	A2	A1	A0	R/W	
1	0	0	0	0	0	0	0	80H

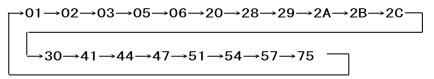
## (5) <u>Select Address & Data</u>

lterree	Select	MSB			Da	ata			LSB	
Items	Address (hex)	D7	D6	D5	D4	D3	D2	D1	D0	
Initial setup 1	01	Advanced switch ON/OFF	0	of Input G Tone/Fade	switch time ain/Volume er/Loudness xing	0	1		ed switch of Mute	
Initial setup 2	02	LPF Phase	0		fer Output elect	0	Sul	owoofer LF	PF fc	
Initial setup 3	03	0	0	0	0	0	0	1	0	
Input Selector	05	Full-diff Type	0	0		Ir	put selector			
Input gain	06	Mute ON/OFF	0	0			Input Gain			
Volume gain	20			١	/olume Gain	/ Attenuation	ı			
Fader 1ch Front	28				Fader Gain /	Attenuation				
Fader 2ch Front	29				Fader Gain / Attenuation					
Fader 1ch Rear	2A				Fader Gain /	Attenuation				
Fader 2ch Rear	2B				Fader Gain /	Attenuation				
Fader Subwoofer	2C				Fader Gain /	Attenuation				
Mixing	30				Mixing Gain	/ Attenuation				
Bass setup	41	0	0	Bas	ss fo	0	0	Ba	.ss Q	
Middle setup	44	0	0	Mide	<b>dle</b> fo	0	0	Mid	dle Q	
Treble setup	47	0	0	Tret	ole f <sub>o</sub>	0	0	0	Treble Q	
Bass gain	51	Bass Boost/ Cut	0	0			Bass Gain			
Middle gain	54	Middle Boost/ Cut	0	0		Ν	/liddle Gain			
Treble gain	57	Treble Boost/ Cut	0	0	0 Treble Gain					
Loudness Gain	75	0	Loudnes	ss Hicut		Lo	udness Gai	n		
System Reset	FE	1	0	0	0	0	0	0	1	

Note

: Advanced switch

- 1. The Advance Switch works in the latch part while changing from one function to another.
- 2. Upon continuous data transfer, the Select Address rolls over because of the automatic increment function, as shown below.



- 3. Advanced switch is not used for the function of input selector, subwoofer output select, etc. Therefore, please apply mute on the side when changing these settings.
- 4. When using mute function of this IC at the time of changing input selector, please switch mute ON/OFF while waiting for advanced-mute time.

## Select address 01 (hex)

Time	MSB	Ac	dvance	ed swit	ch tin	ne of N	/ute	LSB
TITLE	D7	D6	D5	D4	D3	D2	D1	D0
0.6msec	Advanced		Advanced	switch time			0	0
1.0msec	Advanced Switch	0	of Input ga	ain/Volume	0	4	0	1
1.4msec	ON/OFF	0	Tone/Fade	r/Loudness		I	1	0
3.2msec			Mix	king			1	1

Time	MSB	Loudness/Mixing										
	D7	D6	D5	D4	D3	D2	D1	D0				
4.7 msec			0	0								
7.1 msec	Advanced Switch	n 0 <u>0 1</u>	1		4	Advanced switch						
11.2 msec	ON/OFF		1	0	0	1	Time o	of Mute				
14.4 msec			1	1								

Mode	MSB		Advan	ced sv	vitch (	ON/OF	F	LSB
Mode	D7	D6	D5	D4	D3	D2	D1	D0
OFF	0	0	of Input ga	switch time ain/Volume	0	1		ed switch
ON	1	Ŭ	Tone/Fader/Loudness Mixing		Ŭ	-	Time c	of Mute

## Select address 02(hex)

fo	MSB		Sı	lbwoof	er LPF	= fc		LSB
fc	D7	D6	D5	D4	D3	D2	D1	D0
OFF						0	0	0
55Hz						0	0	1
85Hz	LPF	0	Subwoof	er Output	0	0	1	0
120Hz	Phase	0		lect	0	0	1	1
160Hz						1	0	0
Prohibition	]						Other setting	9

Mode	MSB		Subw	oofer (	Dutput	Selec	t	LSB
Mode	D7	D6	D5	D4	D3	D2	D1	D0
LPF			0	0			•	
Front	LPF	0	0	1		0		- ,
Rear	Phase	0	1	0	0	Su	bwoofer LPF	- IC
Prohibition			1	1				

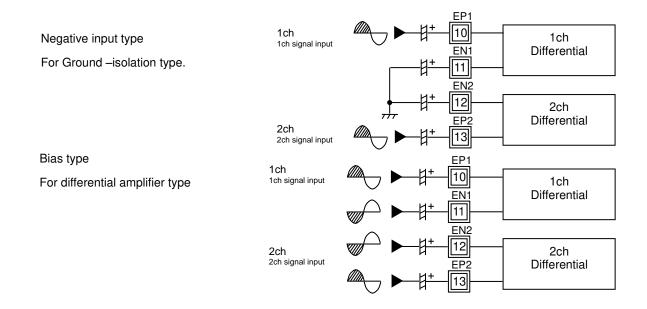
Phase	MSB			LPF F	Phase			LSB
Fliase	D7	D6	D5	D4	D3	D2	D1	D0
0°	0	0	Subwoof	er output	0	Subwoofer LPF fc		
180°	1	0	select		0	50	Dwooler Lr	

#### Select address 05(hex)

Mode			MSB			Input	Selector			LSB
wode	OUTF1	OUTF2	D7	D6	D5	D4	D3	D2	D1	D0
А	A1	A2				0	0	0	0	0
В	B1	B2				0	0	0	0	1
С	C1	C2				0	0	0	1	0
D single	DP1	DP2				0	0	0	1	1
E1 single	EP1	EN1	Full-			0	1	0	1	0
E2 single	EN2	EP2	diff bias	0	0	0	1	0	1	1
A diff	A1	B1	type	0	0	0	1	1	1	1
C diff	B2	C2	select			1	0	0	0	0
D diff	DP1	DP2				0	0	1	1	0
E full diff	EP1	EP2				0	1	0	0	0
Inp	ut SHOR	Т				0	1	0	0	1
Pi	Prohibition						0	ther setting	)	•

**Input SHORT** : The input impedance of each input terminal is lowered from  $100k\Omega(Typ)$  to  $6 k\Omega(Typ)$ . (For quick charge of coupling capacitor)

Mode	MSB	F	ull-d	iff Bias	з Туре	Selec	ct	LSB			
Mode	D7	D6	D5	D4	D3	D2	D1	D0			
Negative Input	0	0	0		lan	ut Solootor					
Bias	1	U	0 0		Input Selector						



Select	address	06 (	(hex)	)
--------	---------	------	-------	---

Mode	MSB			Input	Gain			LSB
wode	D7	D6	D5	D4	D3	D2	D1	D0
0dB				0	0	0	0	0
1dB				0	0	0	0	1
2dB				0	0	0	1	0
3dB				0	0	0	1	1
4dB				0	0	1	0	0
5dB				0	0	1	0	1
6dB				0	0	1	1	0
7dB				0	0	1	1	1
8dB				0	1	0	0	0
9dB				0	1	0	0	1
10dB				0	1	0	1	0
11dB	Mute	0	0	0	1	0	1	1
12dB	ON/OFF	0	0	0	1	1	0	0
13dB				0	1	1	0	1
14dB				0	1	1	1	0
15dB				0	1	1	1	1
16dB				1	0	0	0	0
17dB				1	0	0	0	1
18dB				1	0	0	1	0
19dB				1	0	0	1	1
20dB				1	0	1	0	0
				1	1	0	1	1
Prohibition				:	:	:	:	:
				1	1	1	1	1

Mode	MSB Mute ON/OFF							LSB	
Mode	D7	D6	D5	D4	D3	D2	D1	D0	
OFF	0	0	0			Innut Coin			
ON	1	U	U		Input Gain				

## Select address 20, 28, 29, 2A, 2B, 2C (hex)

Gain & ATT	MSB	Vo	I, Fad	er Gai	n / Att	enuati	ion	LSB
Gain & ATT	D7	D6	D5	D4	D3	D2	D1	D0
	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	0	1
Prohibition	:	:	:	:	:	:	:	:
	0	1	1	1	0	0	0	0
15dB	0	1	1	1	0	0	0	1
14dB	0	1	1	1	0	0	1	0
13dB	0	1	1	1	0	0	1	1
:	:	:	:	:	:	:	:	:
-77dB	1	1	0	0	1	1	0	1
-78dB	1	1	0	0	1	1	1	0
-79dB	1	1	0	0	1	1	1	1
	1	1	0	1	0	0	0	0
Prohibition	:	:	:	:	:	:	:	:
	1	1	1	1	1	1	1	0
-∞dB	1	1	1	1	1	1	1	1

## Select address 30(hex)

Gain & ATT	MSB		Mixing	Gain	/ Atte	nuatio	n	LSB
Gaill & ATT	D7	D6	D5	D4	D3	D2	D1	D0
	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	0	1
Prohibition	:	:	:	:	:	:	:	:
	0	1	1	1	1	0	0	0
7dB	0	1	1	1	1	0	0	1
6dB	0	1	1	1	1	0	1	0
5dB	0	1	1	1	1	0	1	1
:	:	:	:	:	:	:	:	:
-77dB	1	1	0	0	1	1	0	1
-78dB	1	1	0	0	1	1	1	0
-79dB	1	1	0	0	1	1	1	1
	1	1	0	1	0	0	0	0
Prohibition	:	:	•••	•	:	•	:	:
	1	1	1	1	1	1	1	0
MIX OFF	1	1	1	1	1	1	1	1

#### Select address 41(hex)

Q factor	MSB		В	ass	Q fact	or		LSB
Qiactor	D7	D6	D5	D4	D3	D2	D1	D0
0.5							0	0
1.0	0	0	Por	no fa	0	0	0	1
1.5	0	0	Dat	ss f <sub>o</sub>	0	0	1	0
2.0							1	1

fo	MSB			Bass	s fo			LSB
10	D7	D6	D5	D4	D3	D2	D1	D0
60Hz			0	0				
80Hz		0	0	1	0	0	Ba	ass actor
100Hz	0	0	1	0	0	0	Q fa	actor
120Hz			1	1				

## Select address 44(hex)

O factor	MSB		Mi	ddle	Q fac	tor		LSB
Q factor	D7	D6	D5	D4	D3	D2	D1	D0
0.75							0	0
1.0	0	0	Mide	dle fo	0	0	0	1
1.25	0	0	IVIICO		0	0	1	0
1.5							1	1

fa	MSB			Middl	e fo			LSB
10	D7	D6	D5	D4	D3	D2	D1	D0
500Hz			0	0				
1kHz	0	0	0	1	0	0	Mic	ddle
1.5kHz	0	0	1	0	0	0	Q fa	actor
2.5kHz			1	1				

## Select address 47 (hex)

Ofester	MSB		Tre	eble	Q fact	tor		LSB		
Q factor	D7	D6	D5	D4	D3	D2	D1	D0		
0.75	0	٥	Treble fo		0	0	0	0		
1.25	0	0	neb		0	0	0	1		
fo	MSB			Trebl	e fo			LSB		
10	D7	D6	D5	D4	D3	D2	D1	D0		
7.5kHz			0	0						
10kHz	0	0	0	1	0	0	0	Treble		
12.5kHz	0	0	1	0	0	0	0	Q factor		
15kHz			1	1						

#### Select address 51, 54, 57 (hex)

Gain	MSB		E	Bass/Middle	/Treble Gai	n		LSB
Gain	D7	D6	D5	D4	D3	D2	D1	D0
0dB				0	0	0	0	0
1dB				0	0	0	0	1
2dB	]			0	0	0	1	0
3dB				0	0	0	1	1
4dB				0	0	1	0	0
5dB				0	0	1	0	1
6dB				0	0	1	1	0
7dB				0	0	1	1	1
8dB	]			0	1	0	0	0
9dB				0	1	0	0	1
10dB	Bass/			0	1	0	1	0
11dB	Middle/			0	1	0	1	1
12dB	Treble	0	0	0	1	1	0	0
13dB	Boost			0	1	1	0	1
14dB	/cut			0	1	1	1	0
15dB				0	1	1	1	1
16dB				1	0	0	0	0
17dB				1	0	0	0	1
18dB				1	0	0	1	0
19dB				1	0	0	1	1
20dB				1	0	1	0	0
				1	0	1	0	1
Prohibition				-	:	:	:	:
FIUIIIDILIUII				1	1	1	1	0
				1	1	1	1	1

Mode	MSB Bass/Middle/Treble Boost/Cut L								
Mode	D7	D6	D5	D4	D3	D2	D1	D0	
Boost	0	0	0		Beee/	Middle/Trob	a Cain		
Cut	1	0	0	Bass/Middle/Treble Gain					

Mode	MSB		L	Loudness Hicut L						
Mode	D7	D6	D5	D4	D3	D2	D1	C		
Hicut1		0	0			•				
Hicut2	0	0	1			oudness Ga	in			
Hicut3	0	1	0		L	ouuness Ga	111			
Hicut4		1	1							
								LS		
Gain	MSB									
	D7	D6	D5	D4	D3	D2	D1	D		
0dB				0	0	0	0			
1dB				0	0	0	0			
2dB					0	0	1	-		
3dB				0	0	0	1			
4dB				0	0	1	0			
5dB				0	0	1	0			
6dB				0	0	1	1			
7dB				0	0	1	1			
8dB				0	1	0	0			
9dB				0	1	0	0			
10dB				0	1	0	1	(		
11dB	0	Loudno	ss Hicut	0	1	0	1			
12dB	0	Louune	55 mout	0	1	1	0			
13dB				0	1	1	0			
14dB					1	1	1	(		
15dB				0	1	1	1			
16dB				1	0	0	0			
17dB				1	0	0	0			
18dB				1	0	0	1			
19dB				1	0	0	1			
20dB				1	0	1	0			
				1	0	1	0			
Prohibition				:	:	:	:			
				· · 1	· 1	. 1	1	-		

: Initial condition

#### (6) About Power ON Reset

Built-in IC initialization is made during power ON of the supply voltage. Please send initial data to all addresses at supply voltage on. And please turn on mute until this initial data is sent.

Parameter	Symbol	Limit			Unit	Conditions		
Farameter	Symbol	Min	Тур	Max	Unit	Conditions		
Rise Time of VCC	trise	33	-	-	µsec	$V_{CC}$ rise time from 0V to 5V		
VCC Voltage of Release Power ON Reset	VPOR	-	4.1	-	V			

## (7) About External Compulsory Mute Terminal

It is possible to force mute externally by setting an input voltage to the MUTE terminal.

Mute Voltage Condition	Mode			
GND to 1.0V	MUTE ON			
2.3V to V <sub>CC</sub>	MUTE OFF			

Establish the voltage of MUTE in the condition you want to set.

## **Application Information**

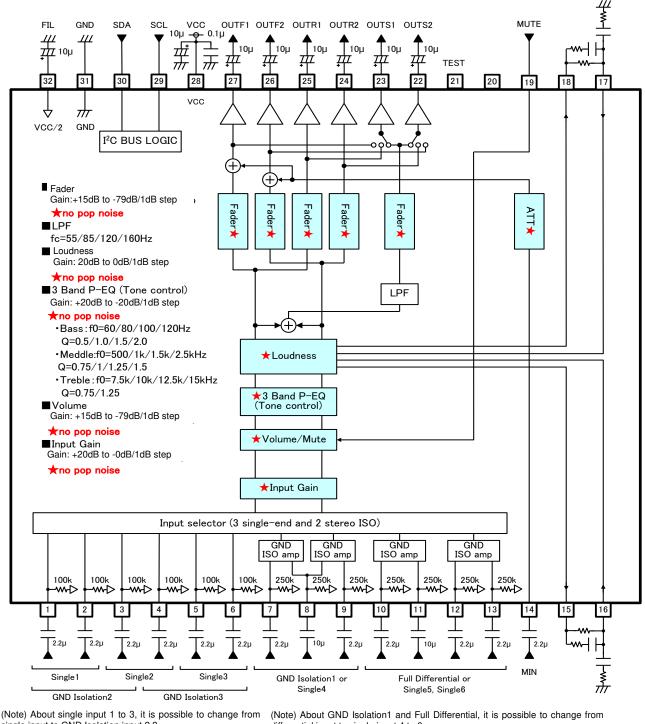
## 1. Function and Specifications

Function			Sp	ecifications							
	· St	ereo inpu	t								
	Single-End/Diff/Full-Diff										
	(Possible to set the number of single-end/diff/full-diff as follows )										
	ĹĹ		Single-End	Differential	Full-Differential						
Input	_	Mode 1	0	3	1						
selector		Mode 2	1	2	1						
	-	Mode 3 Mode 4	3 4	1 0	1						
		Mode 5	5	1	0						
		Mode 6	6	0	0						
Table.1 Combination of input selector											
+20dB to 0dB (1dB step)											
input gain	Input gain         • Possible to use "Advanced switch" for prevention of switching noise.										
Mute	۰Po	ossible to	use "Advanced s	witch" for prevent	tion of switching noise.						
Volume	• +1	15dB to -7	9dB (1dB step),	-∞dB							
	Possible to use "Advanced switch" for prevention of switching noise.										
	<ul> <li>+20dB to -20dB (1dB step)</li> </ul>										
Bass	· Q=0.5, 1, 1.5, 2										
	• f <sub>0</sub> =60, 80, 100, 120Hz										
	Possible to use "Advanced switch" for prevention of switching noise.										
	• +20dB to -20dB (1dB step)										
Middle		=0.75, 1,									
	• fo =500, 1k, 1.5k 2.5kHz										
	Possible to use "Advanced switch" for prevention of switching noise.										
			0dB (1dB step)								
Treble	• Q=0.75, 1.25										
	• f <sub>0</sub> =7.5k, 10k, 12.5k, 15kHz										
					tion of switching noise.						
Fader			9dB(1dB step), -		lion of quitabing point						
				witch for preven	tion of switching noise.						
Loudness			B(1dB step)	witch" for provopt	tion of owitabing poice						
	<ul> <li>Possible to use "Advanced switch" for prevention of switching noise.</li> <li>fc=55/85/120Hz/160Hz, pass</li> </ul>										
LPF		=55/65/12 hase shift	•	5							
		onaural in									
Mixing			dB (1dB step), -∘	∘dB							
					tion of switching noise						
Possible to use "Advanced switch" for prevention of switching noise.											

## 2. Volume / Fader Volume / Mixing Attenuation Data

r					1								1				
(dB)	D7	D6	D5	D4	D3	D2	D1	D0	(dB)	D7	D6	D5	D4	D3	D2	D1	D0
+15	0	1	1	1	0	0	0	1	-33	1	0	1	0	0	0	0	1
+14	0	1	1	1	0	0	1	0	-34	1	0	1	0	0	0	1	0
+13	0	1	1	1	0	0	1	1	-35	1	0	1	0	0	0	1	1
+12	0	1	1	1	0	1	0	0	-36	1	0	1	0	0	1	0	0
+11	0	1	1	1	0	1	0	1	-37	1	0	1	0	0	1	0	1
+10	0	1	1	1	0	1	1	0	-38	1	0	1	0	0	1	1	0
+9	0	1	1	1	0	1	1	1	-39	1	0	1	0	0	1	1	1
+8	0	1	1	1	1	0	0	0	-40	1	0	1	0	1	0	0	0
+7	0	1	1	1	1	0	0	1	-41	1	0	1	0	1	0	0	1
+6	0	1	1	1	1	0	1	0	-42	1	0	1	0	1	0	1	0
+5	0	1	1	1	1	0	1	1	-43	1	0	1	0	1	0	1	1
+4	0	1	1	1	1	1	0	0	-44	1	0	1	0	1	1	0	0
+3	0	1	1	1	1	1	0	1	-45	1	0	1	0	1	1	0	1
+2	0	1	1	1	1	1	1	0	-46	1	0	1	0	1	1	1	0
+1	0	1	1	1	1	1	1	1	-47	1	0	1	0	1	1	1	1
0	1	0	0	0	0	0	0	0	-48	1	0	1	1	0	0	0	0
-1	1	0	0	0	0	0	0	1	-49	1	0	1	1	0	0	0	1
-2	1	0	0	0	0	0	1	0	-50	1	0	1	1	0	0	1	0
-3	1	0	0	0	0	0	1	1	-51	1	0	1	1	0	0	1	1
-4	1	0	0	0	0	1	0	0	-52	1	0	1	1	0	1	0	0
-5	1	0	0	0	0	1	0	1	-53	1	0	1	1	0	1	0	1
-6	1	0	0	0	0	1	1	0	-54	1	0	1	1	0	1	1	0
-7	1	0	0	0	0	1	1	1	-55	1	0	1	1	0	1	1	1
-8	1	0	0	0	1	0	0	0	-56	1	0	1	1	1	0	0	0
-9	1	0	0	0	1	0	0	1	-57	1	0	1	1	1	0	0	1
-10	1	0	0	0	1	0	1	0	-58	1	0	1	1	1	0	1	0
-11	1	0	0	0	1	0	1	1	-59	1	0	1	1	1	0	1	1
-12	1	0	0	0	1	1	0	0	-60	1	0	1	1	1	1	0	0
-13	1	0	0	0	1	1	0	1	-61	1	0	1	1	1	1	0	1
-14	1	0	0	0	1	1	1	0	-62	1	0	1	1	1	1	1	0
-15	1	0	0	0	1	1	1	1	-63	1	0	1	1	1	1	1	1
-16	1	0	0	1	0	0	0	0	-64	1	1	0	0	0	0	0	0
-17	1	0	0	1	0	0	0	1	-65	1	1	0	0	0	0	0	1
-18	1	0	0	1	0	0	1	0	-66	1	1	0	0	0	0	1	0
-19	1	0	0	1	0	0	1	1	-67	1	1	0	0	0	0	1	1
-20	1	0	0	1	0	1	0	0	-68	1	1	0	0	0	1	0	0
-21	1	0	0	1	0	1	0	1	-69	1	1	0	0	0	1	0	1
-22	1	0	0	1	0	1	1	0	-70	1	1	0	0	0	1	1	0
-23	1	0	0	1	0	1	1	1	-71	1	1	0	0	0	1	1	1
-24	1	0	0	1	1	0	0	0	-72	1	1	0	0	1	0	0	0
-25	1	0	0	1	1	0	0	1	-73	1	1	0	0	1	0	0	1
-26	1	0	0	1	1	0	1	0	-74	1	1	0	0	1	0	1	0
-27	1	0	0	1	1	0	1	1	-75	1	1	0	0	1	0	1	1
-28	1	0	0	1	1	1	0	0	-76	1	1	0	0	1	1	0	0
-29	1	0	0	1	1	1	0	1	-77	1	1	0	0	1	1	0	1
-30	1	0	0	1	1	1	1	0	-78	1	1	0	0	1	1	1	0
-31	1	0	0	1	1	1	1	1	-79	1	1	0	0	1	1	1	1
-32	1	0	1	0	0	0	0	0	-∞	1	1	1	1	1	1	1	1
		-	. <u> </u>		-	-	-	. <u> </u>									

Mixing Adjustable range is +7dB to -∞dB.



single input to GND Isolation input 2,3.

differential input to single input 4 to 6.

Unit
R : [Ω]
C : [F]

## Figure 23. BD37543FS

#### Notes on wiring

①Please connect the decoupling capacitor of the power supply in the shortest possible distance to GND. 2 GND lines shall be one-point connected.

③Wiring pattern of Digital shall be away from that of analog unit and crosstalk shall not be acceptable.

 $\tilde{4}$  If possible, SDA and SCL lines of I<sup>2</sup>C BUS shall not be parallel.

The lines shall be shielded, if they are adjacent to each other.

5 If possible, analog input lines should not be parallel. The lines should be shielded, if they are adjacent to each other. 6 About TEST pin (Pin 21), please leave it OPEN.

## **Power Dissipation**

#### About the thermal design of the IC

Characteristics of an IC have a great deal to do with the temperature at which it is used, and exceeding absolute maximum ratings may degrade and destroy elements. Careful consideration must be given to the heat of the IC from the two standpoints of immediate damage and long-term reliability of operation.

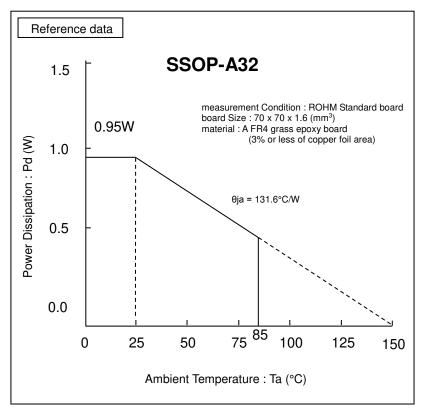


Figure 24. Temperature Derating Curve

(Note) Values are actual measurements and are not guaranteed.

Power dissipation values vary according to the board on which the IC is mounted.

## I/O Equivalent Circuits

Terminal No.	Terminal Name	Terminal Voltage	Equivalent Circuit	Terminal Description
1 2 3 4 5 6	A1 A2 B1 B2 C1 C2	4.25		A terminal for signal input. The input impedance is 100kΩ(typ).
7 8 9 10 11 12 13	DP1 DN DP2 EP1 EN1 EN2 EP2	4.25		Input terminal available to Single/Differential mode. The input impedance is 250kΩ(Typ).
15 18	LDA1 LDA2	4.25	VCC GND GND GND	The loudness characteristic setting terminal.
16 17	LDB1 LDB2	4.25		The loudness characteristic setting terminal.
19	MUTE	-	VCC 0.58×V <sub>CC</sub> 4 250kΩ 1.65V GND	A terminal for external compulsory mute. If terminal voltage is High level, the mute is OFF. And if the terminal voltage is Low level, the mute is on.

Values in the pin explanation and input/output equivalent circuit are reference values only and are not guaranteed.

## I/O Equivalent Circuits – continued

		– continue		
Terminal No.	Terminal Name	Terminal Voltage	Equivalent Circuit	Terminal Description
22 23 24 25 26 27	OUTS2 OUTS1 OUTR2 OUTR1 OUTF2 OUTF1	4.25		A terminal for fader and Subwoofer output.
28	VCC	8.5		Power supply terminal.
29	SCL	-	VCC	A terminal for clock input of I <sup>2</sup> C BUS communication.
30	SDA	-	VCC GND GND GND GND GND GND GND GND GND GND	A terminal for data input of I <sup>2</sup> C BUS communication.
31	GND	0		Ground terminal.
32	FIL	4.25		1/2 VCC terminal. Voltage for reference bias of analog signal system. The simple precharge circuit and simple discharge circuit for an external capacitor are built in.
14	MIN	4.25		A terminal for signal input. The input impedance is 27kΩ (Typ).
21	TEST	-		TEST terminal
L	1			

Values in the pin explanation and input/output equivalent circuit are reference values only and are not guaranteed

## **Operational Notes**

## 1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

## 2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

## 3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

## 4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

## 5. Thermal Consideration

Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

## 6. Recommended Operating Conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

#### 7. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

## 8. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

#### 9. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

#### 10. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

#### 11. Unused Input Pins

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

## **Operational Notes – continued**

## 12. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode. When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

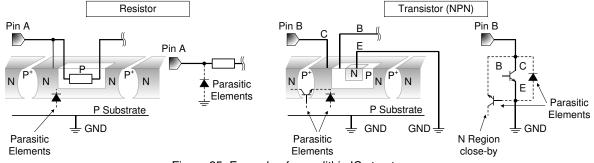
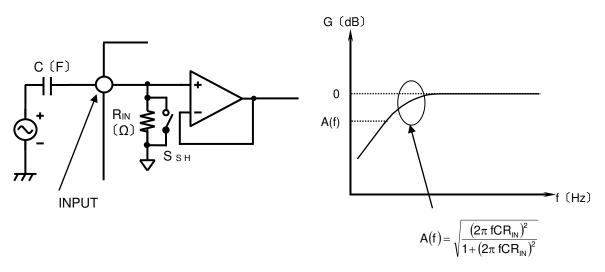


Figure 25. Example of monolithic IC structure

## 13. About Signal Input

(a) About Input Coupling Capacitor Constant Value

The constant value of input coupling capacitor C(F) is decided with respect to the input impedance  $R_{IN}(\Omega)$  at the input signal terminal of the IC. The first HPF characteristic of RC is composed.



#### (b) About the Input Selector SHORT

SHORT mode is the command which makes switch  $S_{SH} = ON$  of input selector part so that the input impedance  $R_{IN}$  of all terminals becomes small. Switch  $S_{SH}$  is OFF when SHORT command is not selected. The constant time brought about by the small resistance inside and the capacitor outside the LSI becomes small when this command is used. The charge time of the capacitor becomes short. Since SHORT mode turns ON the switch of  $S_{SH}$  and makes it low impedance, please use it at no signal condition.

## **Operational Notes – continued**

## 14. About Mute Terminal (Pin 19) when Power Supply is OFF

There should be no applied voltage across the Mute terminal (Pin 19) when power-supply is OFF. If in case voltage is supplied to mute terminal, please insert a series resistor (about  $2.2k\Omega$ ) to Mute terminal. (Please refer to Application Circuit Diagram.)

## 15. About TEST Pin

TEST Pin should be left as OPEN. Pin 21 is TEST Pin.

## 16. About MIX

(1) <u>About Specification of Fader -∞ at MIX ON.</u>

Mix\_signal is added to Main\_signal after Fader\_Gain(+15dB to -79dB) like the figure. When Fader is set at -∞, the signal after a MIX signal is added is done with MUTE because the -∞ circuit of Fader is in the step after the addition circuit

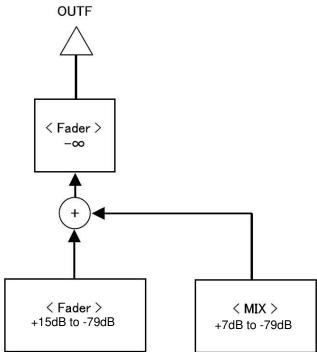
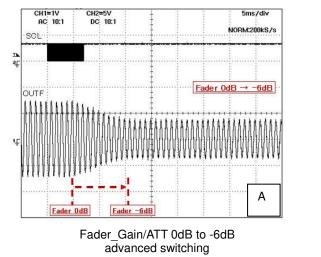
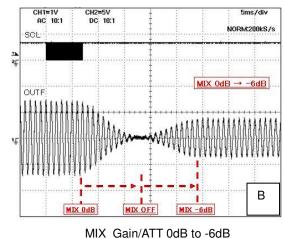


Figure 26. About Front Fader and MIX

(2) About Advanced Switching of MIX Gain/ATT

When advanced switching of MIX\_Gain/ATT works, MIX goes a switching movement that it passes through the state of MIX\_OFF like in B figure below (from current settingof MIX\_Gain/ATT to MIX\_OFF to a target setting of MIX\_Gain/ATT).





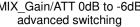


Figure 27. Advanced Switching Movement when MIX\_Gain/ATT is Changed

## **Operational Notes – continued**

## 17. About the External Parts Setting of Loudness Circuit

### This IC is equipped with a Loudness circuit.

The Loudness gain is fixed inside the IC but its frequency characteristic can be changed freely by adjusting the external part filter. The circuit composition of the Loudness part is shown below. Incidentally, when not using the Loudness circuit, please short the pins between LDA1(Pin 15) and LDB1(Pin 16), and between LDA2(Pin 18) and LDB2(Pin 17), so as to avoid the inner amplifier inputs to become floating.

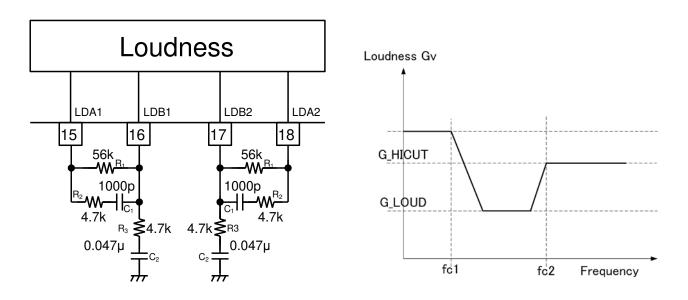


Figure 28. About the External Parts Setting of Loudness Circuit

The Loudness frequency characteristics are decided according to Figure 28. G\_LOUD can be made 20dB when external parts used are the same with Figure 28 (the recommended value). G\_LOUD is the amount of effect of Loudness when Loudness Gain is set at 20dB (P.20).

When Loudness frequency characteristics are changed, each parameter (Gain, Frequency) shown in Figure 28 can be decided using the following approximate equation below.

(Note) Design fc2 value more than one digit bigger than fc1 to get effect on Loudness.

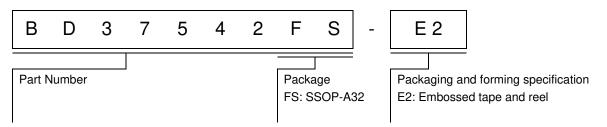
Loudness cut-off frequency

$$fc1 = \frac{1}{2\pi C_2(R_1 + R_3)} [Hz]$$
  
$$fc2 = \frac{1}{2\pi C_1(R_2 + R_3)} [Hz]$$

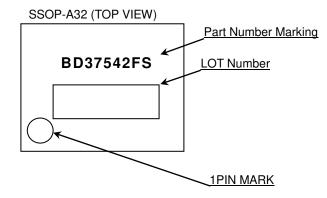
Loudness Gain (The amount of effect of Loudness)

$$\begin{split} \mathbf{G}_{\_\text{LOUD}} &= 20\log\left(\frac{R_3}{R_1 + R_3}\right) \quad \left[ \mathsf{dB} \right] \\ \mathbf{G}_{\_\text{HICUT}} &= 20\log\left(\frac{R_3}{R_1/\!/ R_2 + R_3}\right) \quad \left[ \mathsf{dB} \right] \end{split}$$

## **Ordering Information**



## **Marking Diagram**



## Physical Dimension, Tape and Reel Information SSOP-A32 Package Name $1\ 3.\ 6\pm 0.\ 2$ Max13. 95 (include. BURR) 3 2 日日 H Ħ 3 2 $8\pm 0$ . $4\pm0$ . 3 M I N 7. 21. 0. Ħ Ħ $0.\ 1\ 5\pm0.\ 1$ - $8\pm 0$ . (UNIT:mm)1. 11 PKG:SSOP-A32 Drawing No. EX134-5001-1 0. $36 \pm 0.1$ 0. 8 0. $\bigcirc$ 0. 1 <Tape and Reel information> Embossed carrier tape Таре 2000pcs Quantity E2 Direction The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand of feed С 0 E Direction of feed 1pin Reel \*Order quantity needs to be multiple of the minimum quantity.

## **Revision History**

Date	Revision	Changes
16.Dec.2015	001	New Release

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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSII
CLASSⅣ	CLASSII	CLASSⅢ	CLASSII

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